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Chemical-Mechanical Polishing 2000—Fundamentals and Materials Issues

Editors: Rajiv K. Singh, Rajeev Bajaj, Mansour Moinpour and Marc Meuris

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Chemical-Mechanical Polishing 2000— Fundamentals and Materials Issues

Symposium held April 26–27, 2000, San Francisco, California, U.S.A.

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CONTENTS

Preface ix

Materials Research Society Symposium Proceedings x

CMP MECHANISMS

**The Effect of Wafer Shape on Slurry Film Thickness and Friction
Coefficients in Chemical Mechanical Planarization** E1.2
Joseph Lu, Jonathan Coppeta, Chris Rogers, Vincent P. Manno,
Livia Racz, Ara Philipossian, Mansour Moinpour, and Frank Kaufman

A Model of Chemical Mechanical Polishing E1.4
Ed Paul

Modeling on Mechanical Properties of Polishing Pads in CMP Process E1.5
Takeshi Nishioka, Satoko Iwami, Takashi Kawakami,
Yoshikuni Tateyama, Hiroshi Ohtani, and Naoto Miyashita

Fundamental Studies on the Mechanisms of Oxide CMP E1.7
Uday Mahajan, Seung-Mahn Lee, and Rajiv K. Singh

DIELECTRIC AND METAL CMP

**Planarization of Cu and Ta Using Silica and Alumina Abrasives—
A Comparison** E2.4
Y. Li, S. Ramarajan, M. Hariharaputhiran, Y.S. Her, and S.V. Babu

Chemical Wear of Cu CMP E2.5
Hong Liang, Jean-Michel Martin, Beatrice Vacher, and Vlasta Brusic

*POSTER SESSION:
DIELECTRIC AND METAL CMP*

**A Novel Single Step Lapping and Chemo-Mechanical Polishing
Scheme for Antimonide Based Semiconductors Using 1 µm
Agglomerate-Free Alumina Slurry** E4.1
P.S. Dutta, R.J. Gutmann, D. Keller, and L. Sweet

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Editors: Rajiv K. Singh, Rajeev Bajaj, Mansour Moinpour and Marc Meuris
Frontmatter
[More information](#)

Multi-Level Damascene Process Development: Aluminum CMP	E4.3
David A. Hansen, Gerry Moloney, and Alex Reyes	

**POSTER SESSION:
PROCESS INTEGRATION AND
MANUFACTURABILITY**

Improvement of Wafer Edge Profile and CMP Performance Through the Floating Head Design	E5.1
Huey-Ming Wang, Gerry Moloney, Mario Stella, and Sesinando DeGuzman	

A New Poly-Si CMP Process With Small Erosion for Advanced Trench Isolation Process	E5.3
Naoto Miyashita, Shin-ichiro Uekusa, Takeshi Nishioka, and Satoko Iwami	

The Characteristics of the Electrolyzed D.I. Water With Chemicals and the Outline of the Supply System	E5.4
Mitsuhiko Shirakashi, Kenya Itoh, Ichiro Katakabe, Mamabu Tsujimura, Takayuki Saitoh, Kaoru Yamada, Naoto Miyashita, Masako Kodera, and Yoshitaka Matsui	

**POSTER SESSION:
CMP CONSUMABLES**

An Image Analysis Technique for Assessing Particle Size and Agglomeration Tendency of Slurries	E6.1
Susan R. Machinski, Kathleen A. Richardson, and Aristide Dogariu	

Performance of Polishing Slurries Containing Silica Particles Grown by Sol-Gel Method	E6.5
Sun Hyuk Bae, Jae-Hyun So, Seung-Man Yang, and Do Hyun Kim	

Optical Characterization of Porous Membranes	E6.10
Claudia Mujat, Lorrene Denney, and Aristide Dogariu	

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Frontmatter
[More information](#)

CMP CONSUMABLES

*Interfacial Fluid Pressure and Its Effects on SiO₂ Chemical Mechanical Polishing	E7.1
C. Zhou, L. Shan, J.R. Hight, S.H. Ng, A.J. Paszkowski, J. Tichy, and S. Danyluk	
Dynamic Mechanical Analysis (DMA) of CMP Pad Materials	E7.3
Irene Li, Kersten M. Forsthoefel, Kathleen A. Richardson, Yaw S. Obeng, William G. Easter, and Alvaro Maury	
An Evaluation of the Effects of Benzotriazole in NH₄OH Slurry for Copper CMP	E7.4
V.S.C. Len, D.W. McNeill, and H.S. Gamble	
Fundamental Study of Iodate and Iodine Based Slurries for Copper CMP	E7.8
Seung-Mahn Lee, Uday Mahajan, Zhan Chen, and Rajiv K. Singh	

*PROCESS INTEGRATION AND
MANUFACTURABILITY*

Technique of Surface Control With the Electrolyzed D.I. Water for Post CMP Cleaning	E8.3
Mitsuhiko Shirakashi, Kenya Itoh, Ichiro Katakabe, Masayuki Kamezawa, Sachiko Kihara, Manabu Tsujimura, Takayuki Saitoh, Kaoru Yamada, Naoto Miyashita, Masako Kodera, and Yoshitaka Matsui	
Removal Rate, Uniformity and Defectivity Studies of Chemical Mechanical Polishing of BPSG Films	E8.6
Benjamin A. Bonner, Boris Fishkin, Jeffrey David, Chad Garretson, and Thomas H. Osterheld	
Using Wafer-Scale Patterns for CMP Analysis	E8.8
Brian Lee, Terence Gan, Duane S. Boning, Jeffrey David, Benjamin A. Bonner, Peter McKeever, and Thomas H. Osterheld	
Planarization of Copper Damascene Interconnects by Spin-Etch Process: A Chemical Approach	E8.10
Shyama P. Mukherjee, Joseph A. Levert, and Donald S. DeBear	

Author Index

Subject Index

*Invited Paper

Cambridge University Press

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Frontmatter

[More information](#)

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Frontmatter

[More information](#)

PREFACE

This proceedings volume contains papers from Symposium E, "Fundamentals and Materials Issues in Chemical-Mechanical Polishing of Materials," held April 26–27 at the 2000 MRS Spring Meeting in San Francisco, California. Significant interest and advancements in the field were represented in more than 55 oral and poster presentations. Papers both in the application and fundamentals of CMP were presented at this conference. With the rapid emergence of copper and low dielectric constant materials, the interest in CMP is expected to further accelerate in future years.

We would like to thank all the authors, particularly the invited speakers, the session chairs and referees, all who helped to make this symposium a success. We would like to especially thank Ara Philipossian (University of Arizona), Ajoy Zutshi (Applied Materials), R. Tiwari (Texas Instruments), and S. Das (IBM) for helping us review the manuscripts. It is also our pleasure to acknowledge the support of the Department of Materials Science and Engineering and the Engineering Research Center for Particle Science and Technology at the University of Florida for financial support to this program.

Rajiv K. Singh
Rajeev Bajaj
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